

CHIPMOS TECHNOLOGIES BERMUDA LTD  
Form 6-K  
January 30, 2015

**SECURITIES AND EXCHANGE COMMISSION**

**Washington, DC 20549**

**FORM 6-K**

**REPORT OF FOREIGN PRIVATE ISSUER  
PURSUANT TO RULE 13a-16 OR 15d-16  
OF THE SECURITIES EXCHANGE ACT OF 1934**

**For the month of January, 2015**

**ChipMOS TECHNOLOGIES (Bermuda) LTD.**

**(Translation of Registrant's Name Into English)**

**No. 1, R&D Rd. 1, Hsinchu Science Park**

**Hsinchu, Taiwan**

**Republic of China**

**(Address of Principal Executive Offices)**

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(Indicate by check mark whether the registrant files or will file annual reports under cover of Form 20-F or Form 40-F.)

Form 20-F       Form 40-F

(Indicate by check mark whether the registrant by furnishing the information contained in this form is also thereby furnishing the information to the Commission pursuant to Rule 12g3-2(b) under the Securities Exchange Act of 1934.)

Yes       No

(If Yes is marked, indicate below the file number assigned to the registrant in connection with Rule 12g3-2(b):  
82- .)

**SIGNATURES**

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this report to be signed on its behalf by the undersigned, thereunto duly authorized.

ChipMOS TECHNOLOGIES (Bermuda) LTD.  
(Registrant)

Date: January 30, 2015

By /S/ S. J. Cheng  
Name: S. J. Cheng  
Title: Chairman & Chief Executive Officer

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**ACCRETECH AND ChipMOS TO COOPERATE ON PROCESS AUTOMATION AND EQUIPMENT DEVELOPMENT**

**Hsinchu - 1/30/2015** - ChipMOS TECHNOLOGIES (Bermuda) LTD. ( ChipMOS or the Company ) (Nasdaq: IMOS), an industry leading provider of outsourced semiconductor assembly and test services ( OSAT ), today announced that it has signed a Letter of Intent to cooperate on the development of new equipment and process automation with Tokyo Seimitsu Co., Ltd. ( ACCRETECH ) at ChipMOS 's Tainan fab.

Under the agreement, ACCRETECH will be responsible for the equipment design and manufacturing. This is expected to include, but will not be limited to, probers for wafer testing and wafer dicing equipment. ChipMOS will provide engineering resources for development, testing and evaluation of the jointly-developed new equipment and production lines.

S.J. Cheng, Chairman and Chief Executive Officer of ChipMOS, said, Today 's strategic agreement further builds upon our existing relationship, which started more than 15 years ago. By working in partnership together we believe we can ultimately decrease production costs, enhance production efficiency and increase our already strong respective competitive positions.

**About Tokyo Seimitsu Co., Ltd.:**

Since its foundation in 1949, Tokyo Seimitsu Co., Ltd. ( ACCRETECH ) has consistently focused on developing semiconductor production equipment and measuring instruments that contribute to improving customer 's productivity and on providing good customer support with customer satisfaction as the basic philosophy. ACCRETECH is headquartered in Tokyo and executed its business through affiliate companies in 15 countries around the world. Its stock is listed on Tokyo Stock Exchange under Stock Ticker 7729.

**About ChipMOS TECHNOLOGIES (Bermuda) LTD.:**

ChipMOS TECHNOLOGIES (Bermuda) LTD. ( ChipMOS or the Company ) (NASDAQ: IMOS) (<http://www.chipmos.com>) is an industry leading provider of semiconductor assembly and testing services. With advanced facilities in Hsinchu and Southern Taiwan Science Parks in Taiwan and Shanghai, ChipMOS and its subsidiaries provide testing and assembly services to a broad range of customers, including leading fabless semiconductor companies, integrated device manufacturers and independent semiconductor foundries. The Company 's majority-owned subsidiary, ChipMOS Taiwan, is listed on TWSE under Stock Ticker 8150.

**Forward-Looking Statements**

Certain statements contained in this announcement may be viewed as forward-looking statements within the meaning of Section 27A of the U.S. Securities Act of 1933, as amended, and Section 21E of the U.S. Securities Exchange Act

of 1934, as amended. Such forward-looking statements involve known and unknown risks, uncertainties and other factors, which may cause the actual performance, financial condition or results of operations of the Company to be materially different from any future performance, financial condition or results of operations implied by such forward-looking statements. Further information regarding these risks, uncertainties and other factors are included in the Company's most recent Annual Report on Form 20-F filed with the U.S. Securities and Exchange Commission (the SEC) and in the Company's other filings with the SEC.